

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Yasunori INOUE, et al.

Serial No.: 09/810,420

Filed: March 19, 2001

For: SEMICONDUCTOR DEVICE



Group Art Unit: 2815

Examiner: Sheila V. Clark

Mail Stop Non-Fee Amendment
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Dear Sir:

Transmitted herewith is an Amendment in the above-identified application.

☒
☐
☐

No additional fee is required.

Applicant is entitled to small entity status under 37 CFR 1.27

Also attached:

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	19	22	0	\$18.00 =	\$0.00
Independent Claims	6	6	0	\$84.00 =	\$0.00
Multiple claims newly presented					\$0.00
Fee for extension of time					\$0.00
Total of Above Calculations					\$0.00

☐ Please charge my Deposit Account No. 500417 in the amount of \$0.00. An additional copy of this transmittal sheet is submitted herewith.

☒ The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 500417, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

MCDERMOTT, WILL & EMERY

Wesley L. Strickland

Registration No. 44,363

600 13th Street, N.W.
 Washington, DC 20005-3096
 (202) 756-8000 WLS:lnm
 Facsimile: (202) 756-8087
 Date: May 27, 2003

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Docket No.: 57810-020

PATENT

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#10/B
Amended
C. M. Munnell
5/31/03
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AMENDMENT

Commissioner for Patents
Washington, DC 20231

Sir:

The following remarks and amendments are submitted in response to the non-Final Office Action dated March 26, 2003.

IN THE CLAIMS:

Please amend claims 1, 4, and 6 as shown. A clean version of the amended claims is appended hereto.

1. (Twice Amended) A semiconductor device comprising:

a first semiconductor chip consisting of at least either a circuit against static damage or a passive component;

a second semiconductor chip and a third semiconductor chip installed on a support substrate, wherein said second semiconductor chip and said third semiconductor chip are connected with each other through said first semiconductor chip; and